01 FC:581

State: Texas

___Zip: ⁷⁵²⁶⁵

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

City: Dallas

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jonathan M. Harris, Reg. No. 44,144

Name of Person Signing

May 31, 2002

Date

Total number of pages including cover sheet, attachments, and documents:

ATTORNEY DOCKET NO.

TI-33938P (1962-01600)

PAGE 1 OF I

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with its principal office at P.O. Box 655474, MS 3999, Dallas, Texas 75265, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Ass't Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	PROCESS AND SYSTEM TO PACKAGE RESIDUAL QUANTITIES OF WAFER LEVEL PACKAGES		
SICNATURE OF INVENTOR AND NAME	STEEDIVASAN K. KODURI	Matthew STOVALL	(3)
DATE	5/1/2002	1 MAY 2002	
RESIDENCE (City, County, State)	801 Legacy Dr., #727 Plano, Collin Texas 75023	2420 North Lockhart Sherman, Crayson Texas 75092	
DATE APPLICATION EXECUTED			

After recordation, please return Assignment to:

Mike Skrehot Texas Instruments Incorporated P.O. Box 655474, MS 3999

73332.01/1962.01600

PATENT REEL: 012970 FRAME: 0873 Dallas, TX 75265

73332.01/1962.01600

PATENT
RECORDED: 05/31/2002 REEL: 012970 FRAME: 0874